

SCOPE: SPST/SPDT ANALOG SWITCHES

<u>Device Type</u>	<u>Generic Number</u>	<u>Circuit Function</u>
01	DG417A(x)/883B	CMOS, SPST analog switch
02	DG418A(x)/883B	CMOS, SPST analog switch
03	DG419A(x)/883B	CMOS, SPDT analog switch

Case Outline(s). The case outlines shall be designated in Mil-Std-1835 and as follows:

<u>Outline Letter</u>	<u>Mil-Std-1835</u>	<u>Case Outline</u>	<u>Package Code</u>
Maxim	SMD		
K	P	GDIP1-T08 or CDIP2-T08	J08
L	X	CDFP3-F10	F10

Absolute Maximum Ratings

Voltage Referenced to V^-

V^+	44V
GND	25V
V_L	(GND-0.3V) to (V^+ +0.3V)
Digital Inputs, V_S , V_D <u>1/</u>	(V^- -2V) to (V^+ +2V) or 30mA whichever occurs first.
Continuous Current, Any terminal <u>2</u>	30mA
Peak Current, S or D (Pulsed at 1ms, 10% duty cycle max)	100mA
Lead Temperature (soldering, 10 seconds)	+300°C
Storage Temperature	-65°C to +150°C

Continuous Power Dissipation	T_A = +70°C
8 lead CERDIP (derate 8.0mW/°C above +70°C)	640mW
10 lead FLATPACK (derate 5.3mW/°C above +70°C)	421mW
Junction Temperature T_J	+150°C
Thermal Resistance, Junction to Case, Θ_{JC} :	
Case Outline 8 lead CERDIP	55°C/W
Case Outline 10 lead FLATPACK	85°C/W
Thermal Resistance, Junction to Ambient, Θ_{JA} :	
Case Outline 8 lead CERDIP	125°C/W
Case Outline 10 lead FLATPACK	190°C/W

Recommended Operating Conditions

Ambient Operating Range (T_A)	-55°C to +125°C
Positive Supply Voltage (V^+)	+15V
Negative Supply Voltage (V^-)	-15V
V_{INL} (max)	0.8V
V_{INH} (min)	2.4V
Logic Supply Voltage (V_L)	+5V

1/ Signals on S, D or IN exceeding V^+ or V^- are clamped by internal diodes. Limit forward current to maximum current ratings.

Stresses beyond those listed under “Absolute Maximum Ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

TABLE 1. ELECTRICAL TESTS:

TEST	Symbol	CONDITIONS -55 °C <=T _A <= +125°C V ⁺ =+15V, V ⁻ =-15V, GND=0V V _{INH} =2.4V, V _{INL} =0.8V, V _L =5V Unless otherwise specified		Group A Subgroup	Device type	Limits Min 2/	Limits Max 2/	Units
SWITCH								
Analog-Signal Range	V _{ANALOG}	3/		1,2,3	All	-15	15	V
Drain-Source ON Resistance	r _{DS(ON)}	V ⁺ =+13.5V V ⁻ =-13.5V I _S =-10mA V _D =±12.5V	V _{IN} =0.8V	1 2,3	01	2.5 2.5	35 45	Ω
			V _{IN} =2.4V	1 2,3	02	2.5 2.5	35 45	
			V _{IN} =0.8V, 2.4V 4/	1 2,3	03	2.5 2.5	35 45	
Source-OFF Leakage Current	I _{S(OFF)}	V ⁺ =+16.5V V ⁻ =-16.5V V _D =±15.5V V _S =±15.5V	V _{IN} =2.4V	1 2,3	01	-0.25 -20	0.25 20	nA
			V _{IN} =0.8V	1 2,3	02	-0.25 -20	0.25 20	
			V _{IN} =0.8V, 2.4V 4/	1 2,3	03	-0.25 -20	0.25 20	
Drain-OFF Leakage Current	I _{D(OFF)}	V ⁺ =+16.5V, V ⁻ =-16.5V, V _D =±15.5V, V _S =±15.5V	V _{IN} =2.4V	1 2,3	01	-0.25 -20	0.25 20	nA
			V _{IN} =0.8V	1 2,3	02	-0.25 -20	0.25 20	
			V _{IN} =0.8V, 2.4V 4/	1 2,3	03	-0.75 -60	0.75 60	
Drain-ON Leakage Current	I _{D(ON)}	V ⁺ =+16.5V, V ⁻ =-16.5V, V _D =±15.5V, V _S =±15.5V	V _{IN} =0.8V	1 2,3	01	-0.4 -40	0.4 40	nA
			V _{IN} =2.4V	1 2,3	02	-0.4 -40	0.4 40	
			V _{IN} =0.8V, 2.4V 4/	1 2,3	03	-0.75 -60	0.75 60	
Input Current/Voltage High	I _{INH}	V _{IN} = 2.4V		1,2,3	All	-0.5	0.5	μA
Input Current/Voltage Low	I _{INL}	V _{IN} = 0.8V		1,2,3	All	-0.5	0.5	μA
Positive Supply Current	I+	V ⁺ =+16.5V, V ⁻ =-16.5V, V _{IN} =0V or 5V		1 2,3	All	-1.0 -5.0	1.0 5.0	μA
Negative Supply Current	I-	V ⁺ =+16.5V, V ⁻ =-16.5V, V _{IN} =0V or 5V		1 2,3	All	-1.0 -5.0	1.0 5.0	μA

TABLE 1. ELECTRICAL TESTS:

TEST	Symbol	CONDITIONS -55 °C ≤ T _A ≤ +125 °C V ⁺ = +15V, V ⁻ = -15V, GND = 0V V _{INH} = 2.4V, V _{INL} = 0.8V, V _L = 5V Unless otherwise specified	Group A Subgroup	Device type	Limits Min 2/	Limits Max 2/	Units
Logic Supply Current	I _L	V ⁺ = +16.5V, V ⁻ = -16.5V, V _{IN} = 0V or 5V	1 2,3	All	-1.0 -5.0	1.0 5.0	μA
Ground Current	I _{GND}	V ⁺ = +16.5V, V ⁻ = -16.5V, V _{IN} = 0V or 5V	1 2,3	All	-1.0 -5.0	1.0 5.0	μA
Turn-Off Time	t _{OFF}	V _D = ±10V, R _L = 300Ω, CL = 35pF, Figure 2	9 10,11	01,02		145 210	ns
Transition Time	t _{TRANS}	V _S = ±10V, R _L = 300Ω, CL = 35pF, Figure 3	9 10,11	03		175 250	ns
Break-Before-Make Interval	t _D	V _{S1} = V _{S2} = ±10V, R _L = 300Ω, CL = 35pF, Figure 4	9	03	5	150	ns
Charge Injection 3/	Q	V _{GEN} = 0V, Figure 5	9	All		10	pC
Functional Tests	FT	Verify Truth Table	7,8	All			

NOTE 2: This data sheet uses the algebraic convention, where the most negative value is a minimum and the most positive value is a maximum.

NOTE 3: Guaranteed by design.

NOTE 4: V_{IN} = input voltage to perform proper function.

FIGURE 2: SWITCHING TIME TEST CIRCUIT for DG417/DG418: See Commercial Data Sheet

FIGURE 3: TRANSITION TIME for DG419: See Commercial Data Sheet

FIGURE 4: BREAK-BEFORE-MAKE INTERVAL for DG419: See Commercial Data Sheet

FIGURE 5: CHARGE INJECTION for DG417/DG418/DG419: See Commercial Data Sheet

TRUTH TABLES:

DG417	DG417	DG418	DG418	DG419	DG419	DG419
LOGIC	SWITCH	LOGIC	SWITCH	LOGIC	SWITCH 1	SWITCH 2
0	ON	0	OFF	0	ON	OFF
1	OFF	1	ON	1	OFF	ON

ORDERING INFORMATION:

Package	MAXIM PART	SMD NUMBER
8 pin CERDIP	DG417AK/883B	5962-9073701MPA
10 pin Flatpack	DG417AL/883B	5962-9073701MXC
8 pin CERDIP	DG418AK/883B	5962-9073702MPA
10 pin Flatpack	DG418AL/883B	5962-9073702MXC
8 pin CERDIP	DG419AK/883B	5962-9073703MPA
10 pin Flatpack	DG419AL/883B	5962-9073703MXC

TERMINAL CONNECTIONS:

	DG417/418	DG417/418	DG419	DG419
	J8	F10	J8	F10
1	S	S	D	D
2	NC	NC	S1	S1
3	GND	GND	GND	GND
4	V+	V+	V+	V+
5	V _L	NC	V _L	NC
6	IN	NC	IN	NC
7	V-	V _L	V-	V _L
8	D	IN	S2	IN
9		V-		V-
10		D		S2

QUALITY ASSURANCE

Sampling and inspection procedures shall be in accordance with MIL-Prf-38535, Appendix A as specified in Mil-Std-883.

Screening shall be in accordance with Method 5004 of Mil-Std-883. Burn-in test Method 1015:

1. Test Condition, A, B, C, or D.
2. TA = +125°C minimum.
3. Interim and final electrical test requirements shall be specified in Table 2.

Quality conformance inspection shall be in accordance with Method 5005 of Mil-Std-883, including Groups A, B, C, and D inspection.

Group A inspection:

1. Tests as specified in Table 2.
2. Selected subgroups in Table 1, Method 5005 of Mil-Std-883 shall be omitted.

Group C and D inspections:

- a. End-point electrical parameters shall be specified in Table 1.
- b. Steady-state life test, Method 1005 of Mil-Std-883:
 1. Test condition A, B, C, D.
 2. TA = +125°C, minimum.
 3. Test duration, 1000 hours, except as permitted by Method 1005 of Mil-Std-883.

TABLE 2. ELECTRICAL TEST REQUIREMENTS

Mil-Std-883 Test Requirements	Subgroups per Method 5005, Table 1
Interim Electric Parameters Method 5004	1
Final Electrical Parameters Method 5005	1*, 2, 3, 9, 10, 11
Group A Test Requirements Method 5005	1, 2, 3, 7**, 8**, 9, 10, 11
Group C and D End-Point Electrical Parameters Method 5005	1

* PDA applies to Subgroup 1 only.

** Subgroups 7 and 8 tests shall be sufficient to verify the truth table.